

**CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF
PACKAGE SUBSTRATES**

Appl. No.	:	10/709,427	Confirmation No.	3426
Applicant	:	Cheng-Yen Huang		
Filed	:	May 5, 2004		
TC/A.U.	:	2822		
Examiner	:	Prenty, Mark V		
Docket No.	:	FTCP0036USA0		
Customer No.	:	27765		

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office action of August 03, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 4 of this paper.